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🔍 Title: **WO9113462A1: METHODS OF FORMING ELECTRONIC PACKAGES**

🔍 Derwent Title: Macro-composite body formation for electronic package - uses molten matrix metal to infiltrate desired preform or permeable mass [\[Derwent Record\]](#)

🔍 Country: **WO** World Intellectual Property Organization (WIPO)

🔍 Kind: **A1** Publ. of the Int. Appl. with Int. search report <sup>i</sup> (See also: [WO9113462A2](#), [WO9113462A3](#) )

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🔍 Published / Filed: **1991-09-05 / 1991-02-25**

🔍 Application Number: **WO1991US0001247**

🔍 IPC Code: **H01L 21/48; H01L 23/373;**

🔍 Priority Number: **1990-02-23 US1990000484575**  
**1990-05-09 US1990000520936**

🔍 Abstract: The present invention relates to the formation of a macrocomposite body for use as an electronic package or container. The macrocomposite body is formed by spontaneously infiltrating a permeable mass of filler material (247) or a preform with molten matrix metal (250) and bonding the spontaneously infiltrated material to at least one second material such as a ceramic or ceramic containing body and/or a metal or metal containing body. Moreover, prior to infiltration, the filler material or preform is placed into contact with at least a portion of a second material such that after infiltration of the filler material or preform by molten matrix metal, the infiltrated material is bonded to said second material, thereby forming a macrocomposite body. The macrocomposite body may then be coated by techniques according to the present invention to enhance its performance and/or bonding capabilities. [\[French\]](#)

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[From equivalent WO9113462A2] + -

**+ DESCRIPTION METHODS OF FORMING ELECTRONIC PACKAGES**

**+ TECHNICAL FIELD**

The present invention relates to the formation of a macrocomposite body for use as an electronic package, said macrocomposite body being formed by spontaneously infiltrating a permeable mass of filler material or a preform with molten matrix metal and bonding the spontaneously infiltrated material to at least one second material such as a ceramic and/or a metal, Particularly, an infiltration enhancer and/or infiltration enhancer precursor and/or infiltrating atmosphere are in communication with a filler material or a preform, at least at some point during the process, which permits molten matrix metal to spontaneously infiltrate the filler material or preform. Moreover, prior to infiltration, the filler material or preform is placed into contact with at least a portion of a second material such that after infiltration of the filler material or preform, the infiltrated material is bonded to the second material, thereby forming a macrocomposite body

**+ BACKGROUND ART**

**+ DISCLOSURE OF INVENTION**

**+ BRIEF DESCRIPTION OF DRAWINGS**

⌚ Forward  
References:

Go to Result Set: Forward references (3)

PDF	Patent	Pub.Date	Inventor	Assignee	Title
	<a href="#">US6507105</a>	2003-01-14	Yamagata; Shin-ichi	Sumitomo Electric Industries, Ltd.	Member for semiconductor method for producing the s
	<a href="#">US6486542</a>	2002-11-26	Ohashi; Tsuneaki	NGK Insulators, Ltd	Semiconductor-supporting processes for the production same, joined bodies and pr the production of the same
	<a href="#">US6123895</a>	2000-09-26	Yamagata; Shin-ichi	Sumitomo Electric Industries, Ltd.	Aluminum base member for semiconductor device conta nitrogen rich surface and m producing the same

⌚ Other Abstract  
Info:

None



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